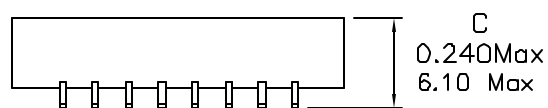
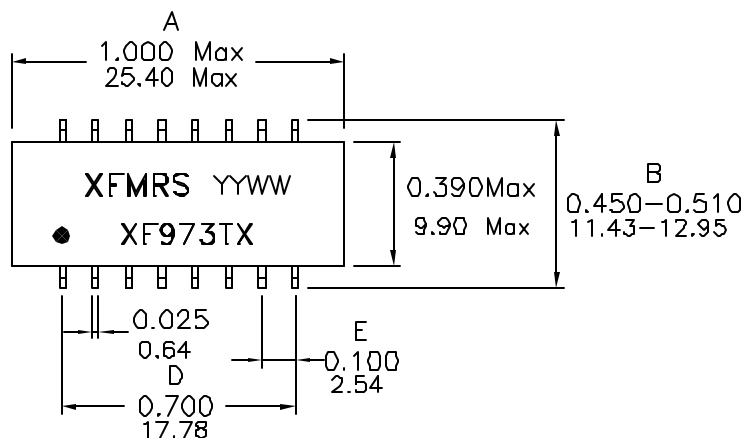
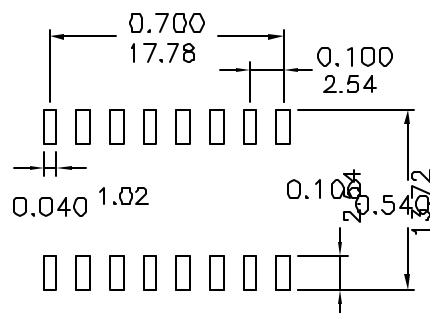


1. Mechanical Dimensions:



CO-PLANARITY $\pm$ 0.004 Max
0.10 Max

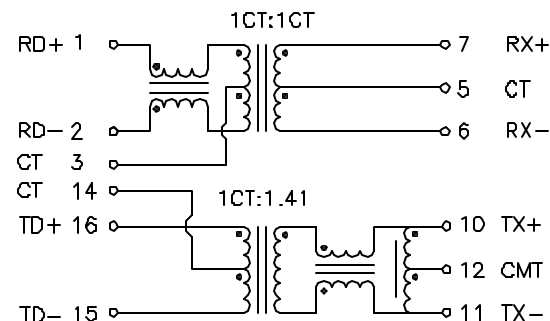


SUGGESTED FOOTPRINT

Notes:

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C, UL file E151558
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: $\pm 0.004"$ (0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

2. Schematic:



3. Electrical Specifications:

Isolation Voltage: 1500 Vrms (Input to Output)

Turns Ratio: 1-3-2:7-5-6 1CT:1CT $\pm$ 3%

Turns Ratio: 16-14-15:10-12-11 1CT:1.41 $\pm$ 3%

CHIP SIDE OCL: 350uH Minimum @0.1Vrms 100KHz 8mA DC

Insertion Loss (300KHz-100MHz): -2.0dB Maximum

Return Loss:

30MHz -18dB Minimum

60MHz -12dB Minimum

80MHz -11dB Minimum

CROSSTALK:

30MHz -45dB Minimum

60MHz -38dB Minimum

80MHz -34dB Minimum

DOC. REV: B/7

PROPRIETARY

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XFMRS Inc. www.XFMRS.com		Title: HIGH SPEED LAN MAGNETICS	
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx $\pm$ 0.010 Inch Dimensions in Inch/mm		P/N: XF973TX	REV. B
		DWN. Juan Mao	Dec-14-06
SCALE 2:1 SHT 1 OF 1		CHK. YK liao	Dec-14-06
		APP. BW	Dec-14-06